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Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
T	1.6mm +/-0.20mm
B	0.6mm +/-0.35mm

  

Packaging Specifications	
Packaging	Waffle, Tray
Packaging Quantity	42

General Information	
Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	87 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches.
Shelf Life	26 Weeks
MSL	1

Specifications	
Capacitance	0.22 uF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	4.5455 GOhms

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